

Amendments to the Claims

1-23.(cancelled)

24.(currently amended) A semiconductor chip package, comprising:

a semiconductor chip having bond pads aligned along a surface of the chip;
insulating material on the surface of the chip, the insulating material having holes therein to enable electrical connection to the bond pads;

conductive leads attached to the insulating material, each lead electrically connected to a bond pad and extending over the surface of the chip bond pads;

a continuous body of encapsulating material, discrete from the insulating material, covering at least a portion of the chip and at least a portion of the conductive leads; and

solder balls each having a first portion disposed in the encapsulating material and contacting a conductive lead and a second portion protruding from the encapsulating material.